Freescale Semiconductor Inc

PART INFORMATION	
Mfg Item Number	A2G22S251-01SR3
Mfg Item Name	NI-400S-240

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-09-18
Response Document ID	00J7K11212D016A1.2
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	

MANUFACTURING	
Mfg Item Number	A2G22S251-01SR3
Mfg Item Name	NI-400S-240
Version	ALL
Weight	2.535300
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Bonding Wire	0.0002						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0002	g	1000000	100		78	0.0078
Cap/Cover	0.5277						g					
Cap/Cover		Metals	Aluminum Oxides (Al2O3)	1344-28-1		0.50178308	g	950887	95.0887		197918	19.7918
Cap/Cover		Plastics/polymers	Epoxy resin, EPON Resin 8091	25928-94-3		0.00191977	g	3638	0.3638		757	0.0757
Cap/Cover		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.01883783	g	35698	3.5698		7430	0.743
Cap/Cover		Glass	Proprietary Material-Other glass compounds (without lead, chromium, cadmium or mercury)	-		0.00515932	g	9777	0.9777		2034	0.2034
Silicon Semiconductor Die	0.0012						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000024	g	20000	2		9	0.0009
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001176	g	980000	98		463	0.0463
Header Assembly	1.99						g					
Header Assembly		Metals	Aluminum Oxides (Al2O3)	1344-28-1		0.0000597	g	30	0.003		23	0.0023
Header Assembly		Metals	Chromium, metal	7440-47-3		0.00033631	g	169	0.0169		132	0.0132
Header Assembly		Metals	Cobalt, metal	7440-48-4		0.01336882	g	6718	0.6718		5273	0.5273
Header Assembly		Metals	Copper, metal	7440-50-8		0.05485236	g	27564	2.7564		21635	2.1635
Header Assembly		Metals	Gold, metal	7440-57-5		0.00500485	g	2515	0.2515		1974	0.1974
Header Assembly		Metals	Iron, metal	7439-89-6		0.07743886	g	38914	3.8914		30544	3.0544
Header Assembly		Metals	Manganese, metal	7439-96-5		0.00164374	g	826	0.0826		648	0.0648
Header Assembly		Metals	Molybdenum, metal	7439-98-7		1.48909312	g	748288	74.8288		587357	58.7357
Header Assembly		Nickel (external applications only)	Nickel	7440-02-0		0.08477002	g	42598	4.2598		33435	3.3435
Header Assembly		Metals	Palladium, metal	7440-05-3		0.04220591	g	21209	2.1209		16647	1.6647
Header Assembly		Metals	Silver, metal	7440-22-4		0.02564513	g	12887	1.2887		10115	1.0115
Header Assembly		Metals	Titanium (III, IV) oxide (Ti3O5)	12065-65-5		0.00016716	g	84	0.0084		65	0.0065
Header Assembly		Plastics/polymers	Ethyl cellulose	9004-57-3		0.00039601	g	199	0.0199		156	0.0156
Header Assembly		Solvents, additives, and other materials	Silicon monoxide	10097-28-6		0.00078008	g	392	0.0392		307	0.0307
Header Assembly		Metals	Copper zinc iron oxide	66402-68-4		0.19423793	g	97607	9.7607		76613	7.6613
Silicon Semiconductor Die	0.0012						g					
Silicon Semiconductor Die		Metals	Gold, metal	7440-57-5		0.00001224	g	10200	1.02		4	0.0004
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00002376	g	19796	1.9796		9	0.0009
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001164	g	970004	97.0004		459	0.0459
Bonding Agent	0.015						g					
Bonding Agent		Solvents, additives, and other materials	Other inorganic compounds.	-		0.00015	g	10000	1		59	0.0059
Bonding Agent		Solvents, additives, and other materials	Other organic compounds.	-		0.00105	g	70000	7		414	0.0414
Bonding Agent		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-8		0.0015	g	100000	10		591	0.0591
Bonding Agent		Metals	Silver, metal	7440-22-4		0.0123	g	820000	82		4851	0.4851

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/A2G22S251-01SR3_IPC1752_v11.xml

http://www.freescale.com/mcds/A2G22S251-01SR3_IPC1752A.xml